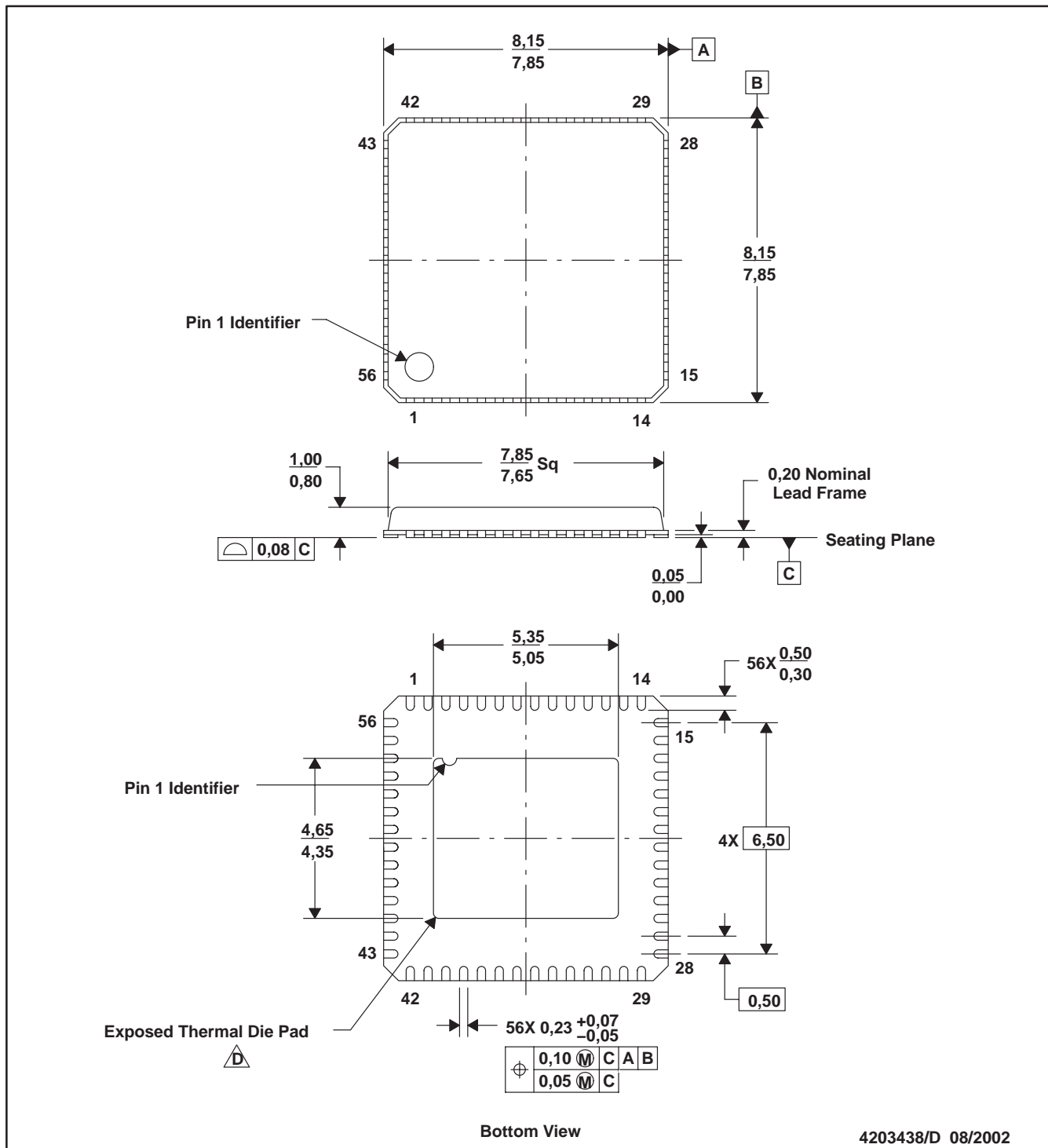


RGQ (S-PQFP-N56)

PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) Package configuration.
 - D. The Package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad may be electrically connected to ground.
 - E. Package registration with JEDEC MO-220 variation VLLD-2.

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